

<b>SPEC SHEET (FOR REFERENCE)</b>	SHEET No.	<b>G05090A</b>	Page.
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TYPE : 6PC2302N1A\*\*

CHIP SIZE	0.56 * 0.43 mm
WAFER SIZE	6 inch
POSSIBLE DIE PER WAFER	64,000 pcs

Maximum Ratings(Ta=25°C)

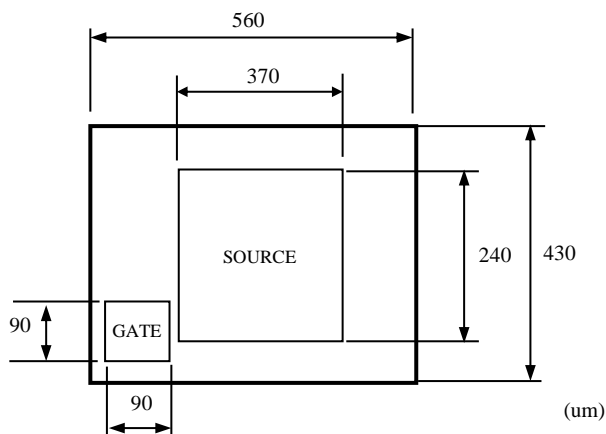
Characteristics	Symbol	Ratings	Unit
Drain-source voltage	VDSS	20	V
Gate-source voltage	VGSS	±8	V
Drain Current (DC)	ID	0.95	A

\* For Reference

WAFER PROBING SPEC (Ta=25°C)

No	MODE	LIMIT				CONDITIONS
		MIN.	Typ	MAX.	UNIT	
1	IGSS			±3	uA	VGS=±8.0V VDS=0V
2	IDSS			500	nA	VDS=20.0V VGS=0V
3	BVDSS	23			V	ID=250uA
4	VTH	0.53		1.1	V	ID=250uA
5	RDS(on)1		0.14	0.23	Ω	ID=600mA VGS=4.5V
6	RDS(on)2		0.2	0.275	Ω	ID=500mA VGS=2.5V
7	RDS(on)3		0.3	0.7	Ω	ID=350mA VGS=1.8V
8	RDS(on)4		0.5	9.5	Ω	ID=40mA VGS=1.5V
9	VSD	0.5		1.1	V	IS=200mA

※ Built-in ZD between Gate and Source.



TENTATIVE

NOTE: